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[Understanding Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	416
Number of Logic Elements/Cells	4160
Total RAM Bits	53248
Number of I/O	183
Number of Gates	263000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k100eqc240-3n

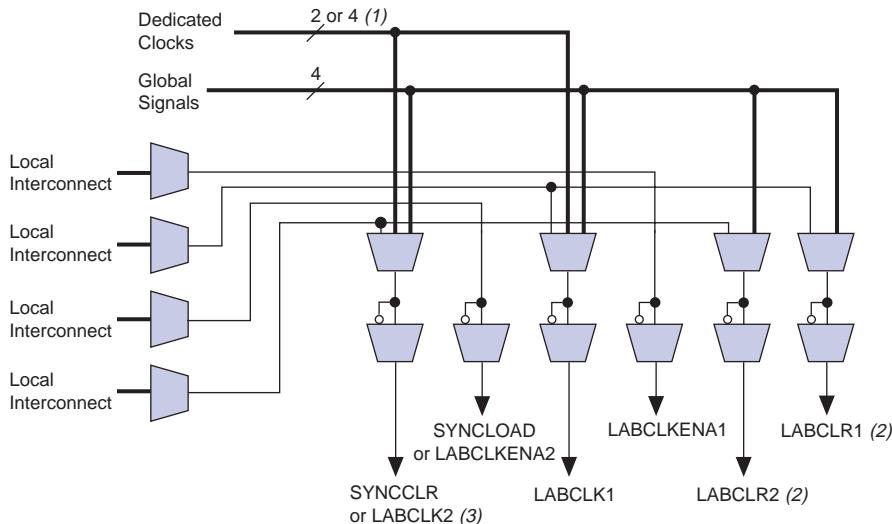
Each LAB contains dedicated logic for driving control signals to its LEs and ESBs. The control signals include clock, clock enable, asynchronous clear, asynchronous preset, asynchronous load, synchronous clear, and synchronous load signals. A maximum of six control signals can be used at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked (e.g., any LE in a particular LAB using CLK1 will also use CLKENA1). LEs with the same clock but different clock enable signals either use both clock signals in one LAB or are placed into separate LABs.

If both the rising and falling edges of a clock are used in a LAB, both LAB-wide clock signals are used.

The LAB-wide control signals can be generated from the LAB local interconnect, global signals, and dedicated clock pins. The inherent low skew of the FastTrack Interconnect enables it to be used for clock distribution. [Figure 4](#) shows the LAB control signal generation circuit.

Figure 4. LAB Control Signal Generation



Notes to Figure 4:

- (1) APEX 20KE devices have four dedicated clocks.
- (2) The LABCLR1 and LABCLR2 signals also control asynchronous load and asynchronous preset for LEs within the LAB.
- (3) The SYNCCLR signal can be generated by the local interconnect or global signals.

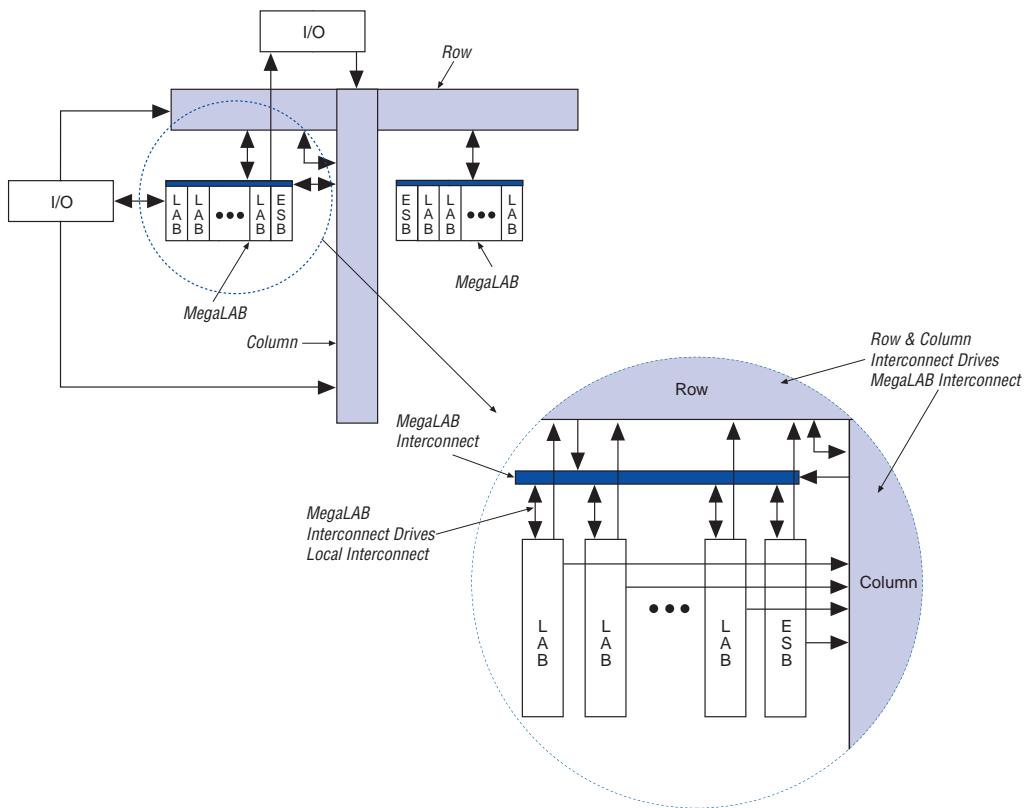
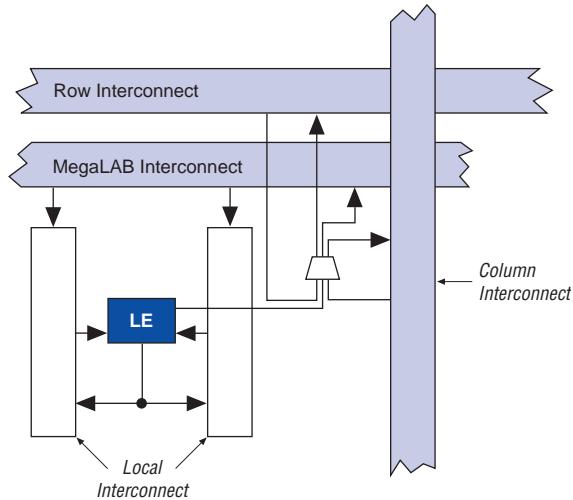
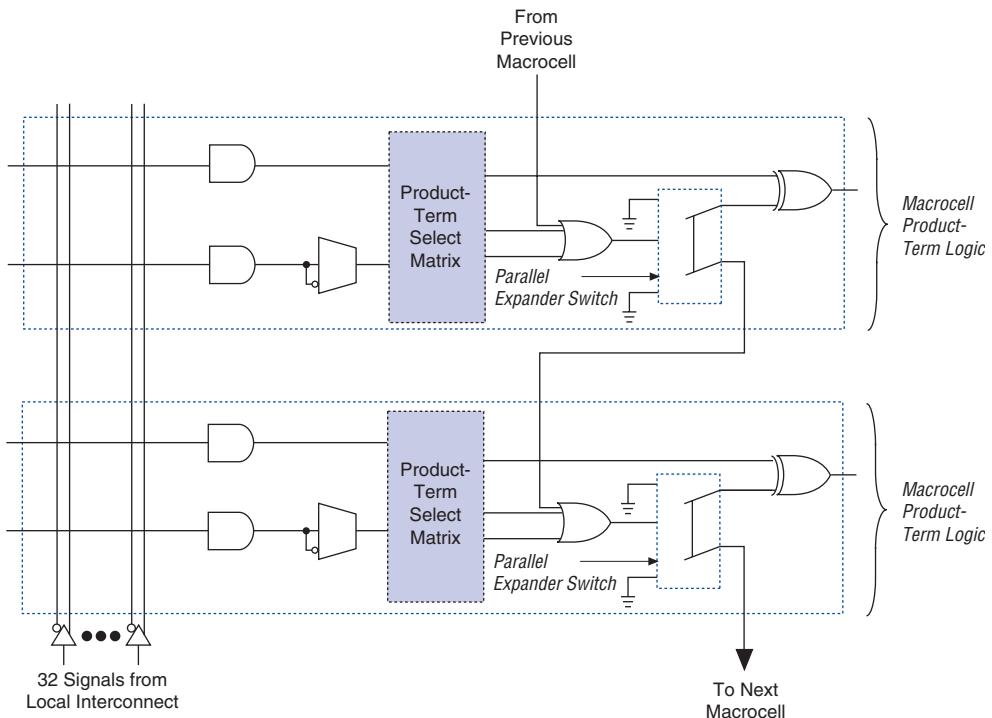
Figure 10. FastTrack Connection to Local Interconnect

Figure 11 shows the intersection of a row and column interconnect, and how these forms of interconnects and LEs drive each other.

Figure 11. Driving the FastTrack Interconnect



APEX 20KE devices include an enhanced interconnect structure for faster routing of input signals with high fan-out. Column I/O pins can drive the FastRow™ interconnect, which routes signals directly into the local interconnect without having to drive through the MegaLAB interconnect. FastRow lines traverse two MegaLAB structures. Also, these pins can drive the local interconnect directly for fast setup times. On EP20K300E and larger devices, the FastRow interconnect drives the two MegaLABs in the top left corner, the two MegaLABs in the top right corner, the two MegaLABs in the bottom left corner, and the two MegaLABs in the bottom right corner. On EP20K200E and smaller devices, FastRow interconnect drives the two MegaLABs on the top and the two MegaLABs on the bottom of the device. On all devices, the FastRow interconnect drives all local interconnect in the appropriate MegaLABs except the local interconnect on the side of the MegaLAB opposite the ESB. Pins using the FastRow interconnect achieve a faster set-up time, as the signal does not need to use a MegaLAB interconnect line to reach the destination LE. **Figure 12** shows the FastRow interconnect.

Figure 16. APEX 20K Parallel Expanders

Embedded System Block

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. [Figure 17](#) shows the ESB block diagram.

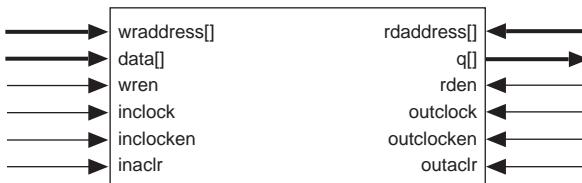
Figure 17. ESB Block Diagram

Figure 23. APEX 20KE CAM Block Diagram

CAM can be used in any application requiring high-speed searches, such as networking, communications, data compression, and cache management.

The APEX 20KE on-chip CAM provides faster system performance than traditional discrete CAM. Integrating CAM and logic into the APEX 20KE device eliminates off-chip and on-chip delays, improving system performance.

When in CAM mode, the ESB implements 32-word, 32-bit CAM. Wider or deeper CAM can be implemented by combining multiple CAMs with some ancillary logic implemented in LEs. The Quartus II software combines ESBs and LEs automatically to create larger CAMs.

CAM supports writing “don’t care” bits into words of the memory. The “don’t-care” bit can be used as a mask for CAM comparisons; any bit set to “don’t-care” has no effect on matches.

The output of the CAM can be encoded or unencoded. When encoded, the ESB outputs an encoded address of the data’s location. For instance, if the data is located in address 12, the ESB output is 12. When unencoded, the ESB uses its 16 outputs to show the location of the data over two clock cycles. In this case, if the data is located in address 12, the 12th output line goes high. When using unencoded outputs, two clock cycles are required to read the output because a 16-bit output bus is used to show the status of 32 words.

The encoded output is better suited for designs that ensure duplicate data is not written into the CAM. If duplicate data is written into two locations, the CAM’s output will be incorrect. If the CAM may contain duplicate data, the unencoded output is a better solution; CAM with unencoded outputs can distinguish multiple data locations.

CAM can be pre-loaded with data during configuration, or it can be written during system operation. In most cases, two clock cycles are required to write each word into CAM. When “don’t-care” bits are used, a third clock cycle is required.

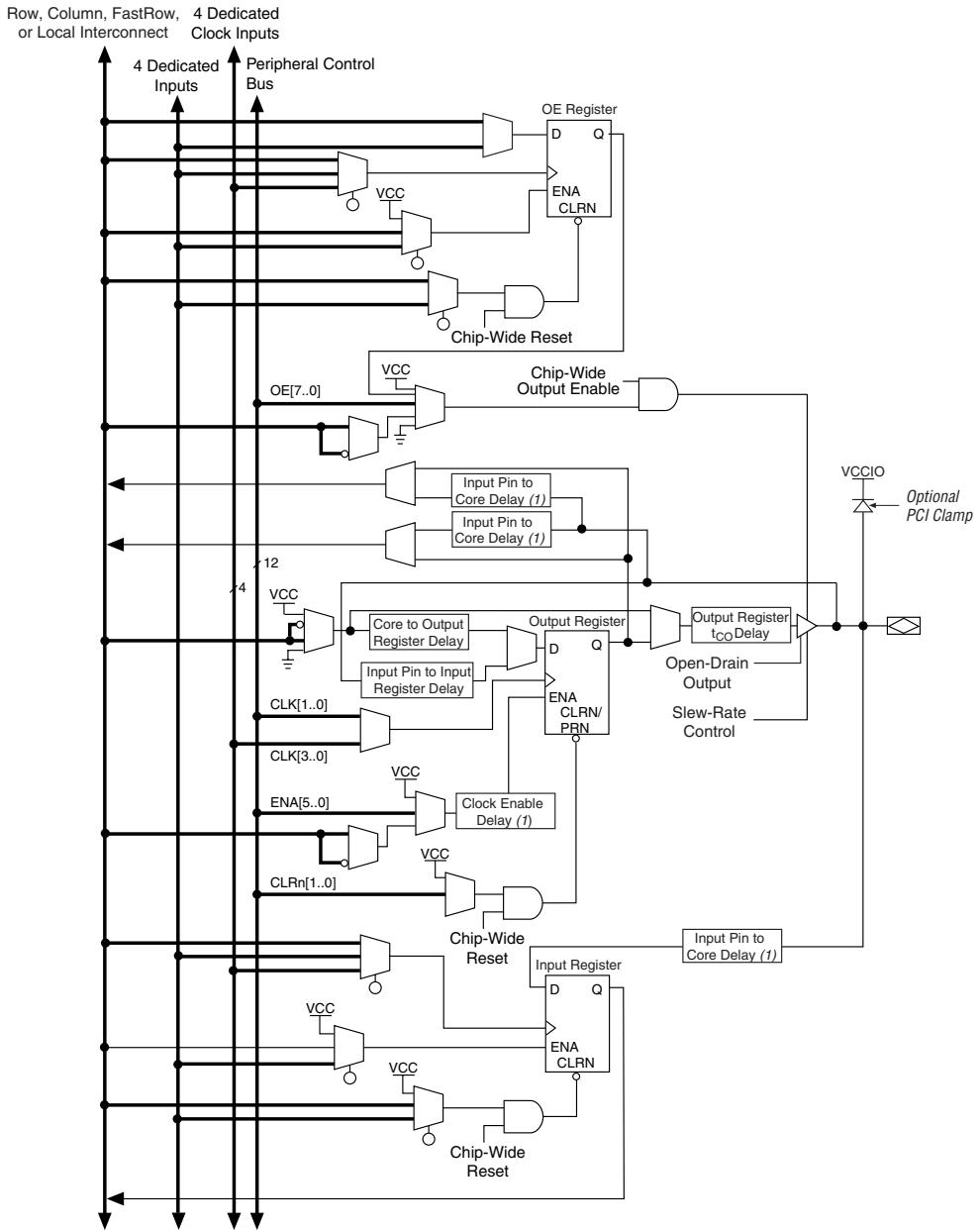
APEX 20KE devices include an enhanced IOE, which drives the FastRow interconnect. The FastRow interconnect connects a column I/O pin directly to the LAB local interconnect within two MegaLAB structures. This feature provides fast setup times for pins that drive high fan-outs with complex logic, such as PCI designs. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The APEX 20KE IOE also includes direct support for open-drain operation, giving faster clock-to-output for open-drain signals. Some programmable delays in the APEX 20KE IOE offer multiple levels of delay to fine-tune setup and hold time requirements. The Quartus II software compiler can set these delays automatically to minimize setup time while providing a zero hold time.

Table 11 describes the APEX 20KE programmable delays and their logic options in the Quartus II software.

Table 11. APEX 20KE Programmable Delay Chains

Programmable Delays	Quartus II Logic Option
Input Pin to Core Delay	Decrease input delay to internal cells
Input Pin to Input Register Delay	Decrease input delay to input registers
Core to Output Register Delay	Decrease input delay to output register
Output Register t_{CO} Delay	Increase delay to output pin
Clock Enable Delay	Increase clock enable delay

The register in the APEX 20KE IOE can be programmed to power-up high or low after configuration is complete. If it is programmed to power-up low, an asynchronous clear can control the register. If it is programmed to power-up high, an asynchronous preset can control the register. [Figure 26](#) shows how fast bidirectional I/O pins are implemented in APEX 20KE devices. This feature is useful for cases where the APEX 20KE device controls an active-low input or another device; it prevents inadvertent activation of the input upon power-up.

Figure 26. APEX 20KE Bidirectional I/O Registers Notes (1), (2)**Notes to Figure 26:**

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

Table 24. APEX 20K 5.0-V Tolerant Device Recommended Operating Conditions Note (2)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage for internal logic and input buffers	(4), (5)	2.375 (2.375)	2.625 (2.625)	V
V_{CCIO}	Supply voltage for output buffers, 3.3-V operation	(4), (5)	3.00 (3.00)	3.60 (3.60)	V
	Supply voltage for output buffers, 2.5-V operation	(4), (5)	2.375 (2.375)	2.625 (2.625)	V
V_I	Input voltage	(3), (6)	-0.5	5.75	V
V_O	Output voltage		0	V_{CCIO}	V
T_J	Junction temperature	For commercial use	0	85	°C
		For industrial use	-40	100	°C
t_R	Input rise time			40	ns
t_F	Input fall time			40	ns

Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 1 of 2) Notes (2), (7), (8)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	High-level input voltage		1.7, 0.5 × V_{CCIO} (9)		5.75	V
V_{IL}	Low-level input voltage		-0.5		0.8, 0.3 × V_{CCIO} (9)	V
V_{OH}	3.3-V high-level TTL output voltage	$I_{OH} = -8 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ (10)	2.4			V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ (10)	$V_{CCIO} - 0.2$			V
	3.3-V high-level PCI output voltage	$I_{OH} = -0.5 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (10)	$0.9 \times V_{CCIO}$			V
	2.5-V high-level output voltage	$I_{OH} = -0.1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (10)	2.1			V
		$I_{OH} = -1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (10)	2.0			V
		$I_{OH} = -2 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (10)	1.7			V

Table 25. APEX 20K 5.0-V Tolerant Device DC Operating Conditions (Part 2 of 2) Notes (2), (7), (8)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{OL}	3.3-V low-level TTL output voltage	$I_{OL} = 12 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ (11)			0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ V}$ (11)			0.2	V
	3.3-V low-level PCI output voltage	$I_{OL} = 1.5 \text{ mA DC}$, $V_{CCIO} = 3.00 \text{ to } 3.60 \text{ V}$ (11)			$0.1 \times V_{CCIO}$	V
	2.5-V low-level output voltage	$I_{OL} = 0.1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (11)			0.2	V
		$I_{OL} = 1 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (11)			0.4	V
		$I_{OL} = 2 \text{ mA DC}$, $V_{CCIO} = 2.30 \text{ V}$ (11)			0.7	V
I_I	Input pin leakage current	$V_I = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	μA
I_{IOZ}	Tri-stated I/O pin leakage current	$V_O = 5.75 \text{ to } -0.5 \text{ V}$	-10		10	μA
I_{CC0}	V _{CC} supply current (standby) (All ESBs in power-down mode)	$V_I = \text{ground, no load, no}$ toggling inputs, -1 speed grade (12)		10		mA
		$V_I = \text{ground, no load, no}$ toggling inputs, -2, -3 speed grades (12)		5		mA
R_{CONF}	Value of I/O pin pull-up resistor before and during configuration	$V_{CCIO} = 3.0 \text{ V}$ (13)	20		50	W
		$V_{CCIO} = 2.375 \text{ V}$ (13)	30		80	W

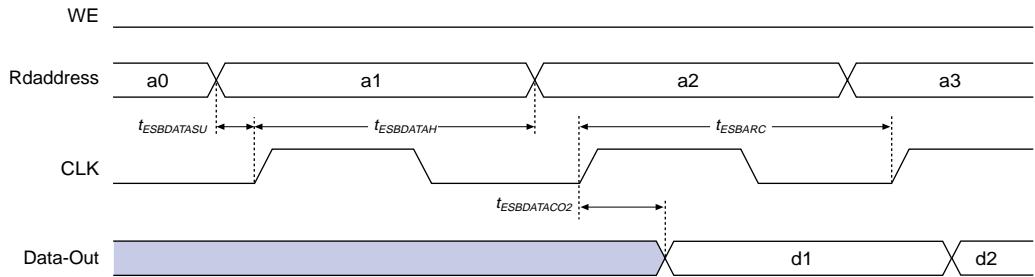
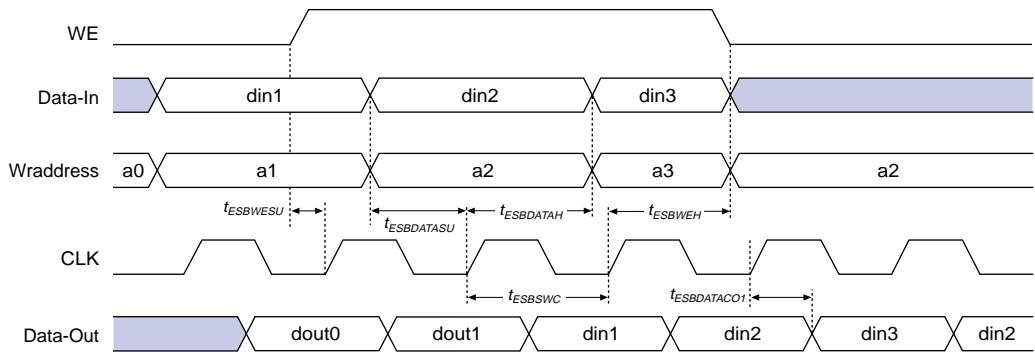
Figure 39. ESB Synchronous Timing Waveforms**ESB Synchronous Read****ESB Synchronous Write (ESB Output Registers Used)**

Figure 40 shows the timing model for bidirectional I/O pin timing.

Table 36. APEX 20KE Routing Timing Microparameters Note (1)

Symbol	Parameter
t_{F1-4}	Fanout delay using Local Interconnect
t_{F5-20}	Fanout delay estimate using MegaLab Interconnect
t_{F20+}	Fanout delay estimate using FastTrack Interconnect

Note to Table 36:

- (1) These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

Table 37. APEX 20KE Functional Timing Microparameters

Symbol	Parameter
TCH	Minimum clock high time from clock pin
TCL	Minimum clock low time from clock pin
TCLR	LE clear Pulse Width
TPREP	LE preset pulse width
TESBCH	Clock high time for ESB
TESBCL	Clock low time for ESB
TESBWP	Write pulse width
TESBRP	Read pulse width

Tables 38 and 39 describe the APEX 20KE external timing parameters.

Table 38. APEX 20KE External Timing Parameters Note (1)

Symbol	Clock Parameter	Conditions
t_{INSU}	Setup time with global clock at IOE input register	
t_{INH}	Hold time with global clock at IOE input register	
t_{OUTCO}	Clock-to-output delay with global clock at IOE output register	$C1 = 10 \text{ pF}$
$t_{INSUPLL}$	Setup time with PLL clock at IOE input register	
t_{INHPLL}	Hold time with PLL clock at IOE input register	
$t_{OUTCOPLL}$	Clock-to-output delay with PLL clock at IOE output register	$C1 = 10 \text{ pF}$

Table 39. APEX 20KE External Bidirectional Timing Parameters *Note (1)*

Symbol	Parameter	Conditions
$t_{INSUBIDIR}$	Setup time for bidirectional pins with global clock at LAB adjacent Input Register	
$t_{INHBIDIR}$	Hold time for bidirectional pins with global clock at LAB adjacent Input Register	
$t_{OUTCOBIDIR}$	Clock-to-output delay for bidirectional pins with global clock at IOE output register	$C_1 = 10 \text{ pF}$
$t_{XZBIDIR}$	Synchronous Output Enable Register to output buffer disable delay	$C_1 = 10 \text{ pF}$
$t_{ZXBIDIR}$	Synchronous Output Enable Register output buffer enable delay	$C_1 = 10 \text{ pF}$
$t_{INSUBDIRPLL}$	Setup time for bidirectional pins with PLL clock at LAB adjacent Input Register	
$t_{INHBIDIRPLL}$	Hold time for bidirectional pins with PLL clock at LAB adjacent Input Register	
$t_{OUTCOBIDIRPLL}$	Clock-to-output delay for bidirectional pins with PLL clock at IOE output register	$C_1 = 10 \text{ pF}$
$t_{XZBIDIRPLL}$	Synchronous Output Enable Register to output buffer disable delay with PLL	$C_1 = 10 \text{ pF}$
$t_{ZXBIDIRPLL}$	Synchronous Output Enable Register output buffer enable delay with PLL	$C_1 = 10 \text{ pF}$

Note to Tables 38 and 39:

- (1) These timing parameters are sample-tested only.

Table 46. EP20K200 External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (1)	1.9		2.3		2.6		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns
t _{XZBIDIR} (1)		5.0		5.9		6.9	ns
t _{ZXBIDIR} (1)		5.0		5.9		6.9	ns
t _{INSUBIDIR} (2)	1.1		1.2		—		ns
t _{INHBIDIR} (2)	0.0		0.0		—		ns
t _{OUTCOBIDIR} (2)	0.5	2.7	0.5	3.1	—	—	ns
t _{XZBIDIR} (2)		4.3		5.0		—	ns
t _{ZXBIDIR} (2)		4.3		5.0		—	ns

Table 47. EP20K400 External Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU} (1)	1.4		1.8		2.0		ns
t _{INH} (1)	0.0		0.0		0.0		ns
t _{OUTCO} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t _{INSU} (2)	0.4		1.0		—		ns
t _{INH} (2)	0.0		0.0		—		ns
t _{OUTCO} (2)	0.5	3.1	0.5	4.1	—	—	ns

Table 48. EP20K400 External Bidirectional Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR} (1)	1.4		1.8		2.0		ns
t _{INHBIDIR} (1)	0.0		0.0		0.0		ns
t _{OUTCOBIDIR} (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
t _{XZBIDIR} (1)		7.3		8.9		10.3	ns
t _{ZXBIDIR} (1)		7.3		8.9		10.3	ns
t _{INSUBIDIR} (2)	0.5		1.0		—		ns
t _{INHBIDIR} (2)	0.0		0.0		—		ns
t _{OUTCOBIDIR} (2)	0.5	3.1	0.5	4.1	—	—	ns
t _{XZBIDIR} (2)		6.2		7.6		—	ns
t _{ZXBIDIR} (2)		6.2		7.6		—	ns

Table 52. EP20K30E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	0.55		0.78		1.15		ns
t _{CL}	0.55		0.78		1.15		ns
t _{CLRP}	0.22		0.31		0.46		ns
t _{PREP}	0.22		0.31		0.46		ns
t _{ESBCH}	0.55		0.78		1.15		ns
t _{ESBCL}	0.55		0.78		1.15		ns
t _{ESBWP}	1.43		2.01		2.97		ns
t _{ESBRP}	1.15		1.62		2.39		ns

Table 53. EP20K30E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.02		2.13		2.24		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	4.88	2.00	5.36	2.00	5.88	ns
t _{INSUPLL}	2.11		2.23		-		ns
t _{INHPPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	2.60	0.50	2.88	-	-	ns

Table 54. EP20K30E External Bidirectional Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	1.85		1.77		1.54		ns
t _{INHBIDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	4.88	2.00	5.36	2.00	5.88	ns
t _{XZBIDIR}		7.48		8.46		9.83	ns
t _{ZXBIDIR}		7.48		8.46		9.83	ns
t _{INSUBIDIRPLL}	4.12		4.24		-		ns
t _{INHBIDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	2.60	0.50	2.88	-	-	ns
t _{XZBIDIRPLL}		5.21		5.99		-	ns
t _{ZXBIDIRPLL}		5.21		5.99		-	ns

Table 56. EP20K60E f_{MAX} ESB Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.83		2.57		3.79	ns
t _{ESBSRC}		2.46		3.26		4.61	ns
t _{ESBAWC}		3.50		4.90		7.23	ns
t _{ESBSWC}		3.77		4.90		6.79	ns
t _{ESBWASU}	1.59		2.23		3.29		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.75		2.46		3.62		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.76		2.47		3.64		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.68		2.49		3.87		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.08		0.43		1.04		ns
t _{ESBDATAH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.29		0.72		1.46		ns
t _{ESBRADDRSU}	0.36		0.81		1.58		ns
t _{ESBDAACO1}		1.06		1.24		1.55	ns
t _{ESBDAACO2}		2.39		3.35		4.94	ns
t _{ESBDD}		3.50		4.90		7.23	ns
t _{PD}		1.72		2.41		3.56	ns
t _{PTERMSU}	0.99		1.56		2.55		ns
t _{TERMCO}		1.07		1.26		1.08	ns

Table 74. EP20K200E f_{MAX} ESB Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.68		2.06		2.24	ns
t _{ESBSRC}		2.27		2.77		3.18	ns
t _{ESBAWC}		3.10		3.86		4.50	ns
t _{ESBSWC}		2.90		3.67		4.21	ns
t _{ESBWASU}	0.55		0.67		0.74		ns
t _{ESBWAH}	0.36		0.46		0.48		ns
t _{ESBWDSU}	0.69		0.83		0.95		ns
t _{ESBWDH}	0.36		0.46		0.48		ns
t _{ESBRASU}	1.61		1.90		2.09		ns
t _{ESBRAH}	0.00		0.00		0.01		ns
t _{ESBWESU}	1.42		1.71		2.01		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	-0.06		-0.07		0.05		ns
t _{ESBDAZH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.11		0.13		0.31		ns
t _{ESBRAADDRSU}	0.18		0.23		0.39		ns
t _{ESBDAZCO1}		1.09		1.35		1.51	ns
t _{ESBDAZCO2}		2.19		2.75		3.22	ns
t _{ESBDD}		2.75		3.41		4.03	ns
t _{PD}		1.58		1.97		2.33	ns
t _{PTERMSU}	1.00		1.22		1.51		ns
t _{PTERMCO}		1.10		1.37		1.09	ns

Table 75. EP20K200E f_{MAX} Routing Delays

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.25		0.27		0.29	ns
t _{F5-20}		1.02		1.20		1.41	ns
t _{F20+}		1.99		2.23		2.53	ns

Table 76. EP20K200E Minimum Pulse Width Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{CH}	1.36		2.44		2.65		ns
t _{CCL}	1.36		2.44		2.65		ns
t _{CLRP}	0.18		0.19		0.21		ns
t _{PREP}	0.18		0.19		0.21		ns
t _{ESBCH}	1.36		2.44		2.65		ns
t _{ESBCL}	1.36		2.44		2.65		ns
t _{ESBWP}	1.18		1.48		1.76		ns
t _{ESBRP}	0.95		1.17		1.41		ns

Table 77. EP20K200E External Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.24		2.35		2.47		ns
t _{INH}	0.00		0.00		0.00		ns
t _{OUTCO}	2.00	5.12	2.00	5.62	2.00	6.11	ns
t _{INSUPLL}	2.13		2.07		-		ns
t _{INHPLL}	0.00		0.00		-		ns
t _{OUTCOPLL}	0.50	3.01	0.50	3.36	-	-	ns

Table 78. EP20K200E External Bidirectional Timing Parameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.81		3.19		3.54		ns
t _{INHBDIR}	0.00		0.00		0.00		ns
t _{OUTCOBIDIR}	2.00	5.12	2.00	5.62	2.00	6.11	ns
t _{XZBIDIR}		7.51		8.32		8.67	ns
t _{ZXBIDIR}		7.51		8.32		8.67	ns
t _{INSUBIDIRPLL}	3.30		3.64		-		ns
t _{INHBDIRPLL}	0.00		0.00		-		ns
t _{OUTCOBIDIRPLL}	0.50	3.01	0.50	3.36	-	-	ns
t _{XZBIDIRPLL}		5.40		6.05		-	ns
t _{ZXBIDIRPLL}		5.40		6.05		-	ns

Tables 79 through 84 describe f_{MAX} LE Timing Microparameters, f_{MAX} ESB Timing Microparameters, f_{MAX} Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K300E APEX 20KE devices.

Table 79. EP20K300E f_{MAX} LE Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{SU}	0.16		0.17		0.18		ns
t _H	0.31		0.33		0.38		ns
t _{CO}		0.28		0.38		0.51	ns
t _{LUT}		0.79		1.07		1.43	ns

Table 80. EP20K300E f_{MAX} ESB Timing Microparameters

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{ESBARC}		1.79		2.44		3.25	ns
t _{ESBSRC}		2.40		3.12		4.01	ns
t _{ESBAWC}		3.41		4.65		6.20	ns
t _{ESBSWC}		3.68		4.68		5.93	ns
t _{ESBWASU}	1.55		2.12		2.83		ns
t _{ESBWAH}	0.00		0.00		0.00		ns
t _{ESBWDSU}	1.71		2.33		3.11		ns
t _{ESBWDH}	0.00		0.00		0.00		ns
t _{ESBRASU}	1.72		2.34		3.13		ns
t _{ESBRAH}	0.00		0.00		0.00		ns
t _{ESBWESU}	1.63		2.36		3.28		ns
t _{ESBWEH}	0.00		0.00		0.00		ns
t _{ESBDATASU}	0.07		0.39		0.80		ns
t _{ESBDAZH}	0.13		0.13		0.13		ns
t _{ESBWADDRSU}	0.27		0.67		1.17		ns
t _{ESBRAADDRSU}	0.34		0.75		1.28		ns
t _{ESBDAZCO1}		1.03		1.20		1.40	ns
t _{ESBDAZCO2}		2.33		3.18		4.24	ns
t _{ESBDD}		3.41		4.65		6.20	ns
t _{PD}		1.68		2.29		3.06	ns
t _{PTERMSU}	0.96		1.48		2.14		ns
t _{PTERMCO}		1.05		1.22		1.42	ns

Table 81. EP20K300E f_{MAX} Routing Delays

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
t _{F1-4}		0.22		0.24		0.26	ns
t _{F5-20}		1.33		1.43		1.58	ns
t _{F20+}		3.63		3.93		4.35	ns

Table 87. EP20K400E f_{MAX} Routing Delays

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{F1-4}		0.25		0.25		0.26	ns
t_{F5-20}		1.01		1.12		1.25	ns
t_{F20+}		3.71		3.92		4.17	ns

Table 88. EP20K400E Minimum Pulse Width Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	1.36		2.22		2.35		ns
t_{CL}	1.36		2.26		2.35		ns
t_{CLRP}	0.18		0.18		0.19		ns
t_{PREP}	0.18		0.18		0.19		ns
t_{ESBCH}	1.36		2.26		2.35		ns
t_{ESBCL}	1.36		2.26		2.35		ns
t_{ESBWP}	1.17		1.38		1.56		ns
t_{ESBRP}	0.94		1.09		1.25		ns

Table 89. EP20K400E External Timing Parameters

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.51		2.64		2.77		ns
t_{INH}	0.00		0.00		0.00		ns
t_{OUTCO}	2.00	5.25	2.00	5.79	2.00	6.32	ns
$t_{INSUPLL}$	3.221		3.38		-		ns
t_{INHPLL}	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	2.25	0.50	2.45	-	-	ns